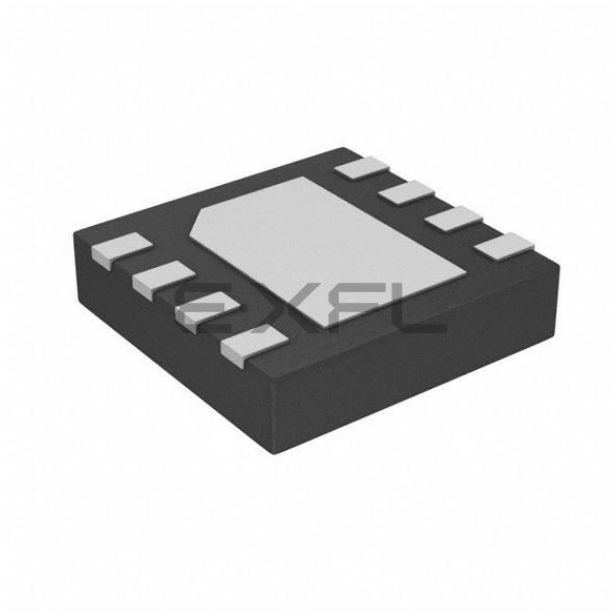


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	6
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	224 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 5x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf15313-e-rf

1.0 DEVICE OVERVIEW

The PIC16(L)F15313/23 are described within this data sheet. The PIC16(L)F15313/23 devices are available in 8/14-pin PDIP, SSOP, SOIC, DFN, and UQFN packages. Figure 1-1 and Figure 1-2 shows the block diagrams of the PIC16(L)F15313/23 devices. Table 1-2 and Table 1-3 shows the pinout descriptions.

Reference Table 1-1 for peripherals available per device.

TABLE 1-1: DEVICE PERIPHERAL SUMMARY

Peripheral		PIC16(L)F15313	PIC16(L)F15323
Analog-to-Digital Converter		●	●
Digital-to-Analog Converter (DAC1)		●	●
Fixed Voltage Reference (FVR)		●	●
Numerically Controlled Oscillator (NCO1)		●	●
Temperature Indicator Module (TIM)		●	●
Zero-Cross Detect (ZCD1)		●	●
Capture/Compare/PWM Modules (CCP)			
	CCP1	●	●
	CCP2	●	●
Comparator Module (Cx)			
	C1	●	●
	C2		●
Configurable Logic Cell (CLC)			
	CLC1	●	●
	CLC2	●	●
	CLC3	●	●
	CLC4	●	●
Complementary Waveform Generator (CWG)			
	CWG1	●	●
Enhanced Universal Synchronous/Asynchronous Receiver/Transmitter (EUSART)			
	EUSART1	●	●
Master Synchronous Serial Ports (MSSP)			
	MSSP1	●	●
Pulse-Width Modulator (PWM)			
	PWM3	●	●
	PWM4	●	●
	PWM5	●	●
	PWM6	●	●
Timers			
	Timer0	●	●
	Timer1	●	●
	Timer2	●	●

TABLE 1-2: PIC16(L)F15313 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RA3/$\overline{SS1}$(1)/CLCIN0(1)/VPP/$\overline{MCLR}$/IOCA3	RA3	TTL/ST	CMOS/OD	General purpose I/O.
	$\overline{SS1}$(1)	TTL/ST	—	MSSP1 SPI slave select input.
	CLCIN0(1)	TTL/ST	—	Configurable Logic Cell source input.
	VPP	HV	—	ICSP™ High-Voltage Programming mode entry input.
	$\overline{MCLR}$	ST	—	Master clear input with internal weak pull up resistor.
	IOCA3	TTL/ST	—	Interrupt-on-change input.
RA4/ANA4/C1IN1-/T1G(1)/CLKOUT/OSC2/IOCA4	RA4	TTL/ST	CMOS/OD	General purpose I/O.
	ANA4	AN	—	ADC Channel A4 input.
	C1IN1-	AN	—	Comparator 1 negative input.
	T1G(1)	ST	—	Timer1 Gate input.
	CLKOUT	—	CMOS/OD	FOSC/4 digital output (in non-crystal/resonator modes).
	OSC2	—	XTAL	External Crystal/Resonator (LP, XT, HS modes) driver output.
	IOCA4	TTL/ST	—	Interrupt-on-change input.
RA5/ANA5/ADACT(1)/T1CKI(1)/T2IN(1)/CCP1(1)/CCP2(1)/CLCIN1(1)/CLKIN/OSC1/EIN/IOCA5	RA5	TTL/ST	CMOS/OD	General purpose I/O.
	ANA5	AN	—	ADC Channel A5 input.
	ADACT(1)	TTL/ST	—	ADC Auto-Conversion Trigger input.
	T1CKI(1)	TTL/ST	—	Timer1 external digital clock input.
	T2IN(1)	TTL/ST	—	Timer2 external input.
	CCP1(1)	TTL/ST	CMOS/OD	Capture/compare/PWM1 (default input location for capture function).
	CCP2(1)	TTL/ST	CMOS/OD	Capture/compare/PWM2 (default input location for capture function).
	CLCIN1(1)	TTL/ST	—	Configurable Logic Cell source input.
	CLKIN	TTL/ST	—	External digital clock input.
	OSC1	XTAL	—	External Crystal/Resonator (LP, XT, HS modes) driver input.
	EIN	TTL/ST	—	External digital clock input.
	IOCA5	TTL/ST	—	Interrupt-on-change input.
VDD	VDD	Power	—	Positive supply voltage input.
VSS	VSS	Power	—	Ground reference.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open-Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C
HV = High Voltage; XTAL = Crystal levels

Note 1: This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to Table 15-3 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 15-3.

3: This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.

4: These pins are configured for I^2C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I^2C specific or SMBus input buffer thresholds.

TABLE 4-6: PIC16(L)F15313/23 MEMORY MAP, BANKS 16-23

	BANK 16		BANK 17		BANK 18		BANK 19		BANK 20		BANK 21		BANK 22		BANK 23
800h	Core Register (Table 4-3)	880h	Core Register (Table 4-3)	900h	Core Register (Table 4-3)	980h	Core Register (Table 4-3)	A00h	Core Register (Table 4-3)	A80h	Core Register (Table 4-3)	B00h	Core Register (Table 4-3)	B80h	Core Register (Table 4-3)
80Bh		88Bh		90Bh		98Bh		A0Bh		A8Bh		B0Bh		B8Bh	
80Ch	WDTCON0	88Ch	CPUDOZE	90Ch	FVRCON	98Ch	—	A0Ch	—	A8Ch	—	B0Ch	—	B8Ch	—
80Dh	WDTCON1	88Dh	OSCCON1	90Dh	—	98Dh	—	A0Dh	—	A8Dh	—	B0Dh	—	B8Dh	—
80Eh	WDTL	88Eh	OSCCON2	90Eh	DAC1CON0	98Eh	—	A0Eh	—	A8Eh	—	B0Eh	—	B8Eh	—
80Fh	WDTH	88Fh	OSCCON3	90Fh	DAC1CON1	98Fh	CMOUT	A0Fh	—	A8Fh	—	B0Fh	—	B8Fh	—
810h	WDTU	890h	OSCSTAT1	910h	—	990h	CM1CON0	A10h	—	A90h	—	B10h	—	B90h	—
811h	BORCON	891h	OSCEN	911h	—	991h	CM1CON1	A11h	—	A91h	—	B11h	—	B91h	—
812h	VREGCON(2)	892h	OSCTUNE	912h	—	992h	CM1NCH	A12h	—	A92h	—	B12h	—	B92h	—
813h	PCON0	893h	OSCFRQ	913h	—	993h	CM1PCH	A13h	—	A93h	—	B13h	—	B93h	—
814h	PCON1	894h	—	914h	—	994h	CM2CON0(3)	A14h	—	A94h	—	B14h	—	B94h	—
815h	—	895h	CLKRCON	915h	—	995h	CM2CON1(3)	A15h	—	A95h	—	B15h	—	B95h	—
816h	—	896h	CLKCLK	916h	—	996h	CM2NCH(3)	A16h	—	A96h	—	B16h	—	B96h	—
817h	—	897h	—	917h	—	997h	CM2PCH(3)	A17h	—	A97h	—	B17h	—	B97h	—
818h	—	898h	—	918h	—	998h	—	A18h	—	A98h	—	B18h	—	B98h	—
819h	—	899h	—	919h	—	999h	—	A19h	—	A99h	—	B19h	—	B99h	—
81Ah	NVMADRL	89Ah	—	91Ah	—	99Ah	—	A1Ah	—	A9Ah	—	B1Ah	—	B9Ah	—
81Bh	NVMADRH	89Bh	—	91Bh	—	99Bh	—	A1Bh	—	A9Bh	—	B1Bh	—	B9Bh	—
81Ch	NVMDATL	89Ch	—	91Ch	—	99Ch	—	A1Ch	—	A9Ch	—	B1Ch	—	B9Ch	—
81Dh	NVMDATH	89Dh	—	91Dh	—	99Dh	—	A1Dh	—	A9Dh	—	B1Dh	—	B9Dh	—
81Eh	NVMCON1	89Eh	—	91Eh	—	99Eh	—	A1Eh	—	A9Eh	—	B1Eh	—	B9Eh	—
81Fh	NVMCON2	89Fh	—	91Fh	ZCDCON	99Fh	—	A1Fh	—	A9Fh	—	B1Fh	—	B9Fh	—
820h	Unimplemented Read as '0'	8A0h	Unimplemented Read as '0'	920h	Unimplemented Read as '0'	9A0h	Unimplemented Read as '0'	A20h	Unimplemented Read as '0'	AA0h	Unimplemented Read as '0'	B20h	Unimplemented Read as '0'	BA0h	Unimplemented Read as '0'
86Fh		8EFh		96Fh		9EFh		A6Fh		AEFh		B6Fh		BEFh	
870h	Common RAM Accesses 70h-7Fh	8F0h	Common RAM Accesses 70h-7Fh	970h	Common RAM Accesses 70h-7Fh	9F0h	Common RAM Accesses 70h-7Fh	A70h	Common RAM Accesses 70h-7Fh	AF0h	Common RAM Accesses 70h-7Fh	B70h	Common RAM Accesses 70h-7Fh	BF0h	Common RAM Accesses 70h-7Fh
87Fh		8FFh		97Fh		9FFh		A7Fh		AFFh		B7Fh		BFFh	

Note 1: Unimplemented locations read as '0'.
2: Register not implemented on LF devices.
3: Present only on PIC16(L)F15323.

TABLE 4-10: SPECIAL FUNCTION REGISTER SUMMARY BANKS 0-63 (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on: MCLR
Bank 2											
CPU CORE REGISTERS; see Table 4-3 for specifics											
10Ch — 118h	—	Unimplemented								—	—
119h	RC1REG	EUSART Receive Data Register								0000 0000	0000 0000
11Ah	TX1REG	EUSART Transmit Data Register								0000 0000	0000 0000
11Bh	SP1BRGL	SP1BRG<7:0>								0000 0000	0000 0000
11Ch	SP1BRGH	SP1BRG<15:8>								0000 0000	0000 0000
11Dh	RC1STA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 0000	0000 0000
11Eh	TX1STA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010	0000 0010
11Fh	BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	01-0 0-00	01-0 0-00

Legend: x = unknown, u = unchanged, q = depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

REGISTER 5-2: CONFIGURATION WORD 2: SUPERVISORS

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
$\overline{\text{DEBUG}}$	STVREN	PPS1WAY	ZCDDIS	BORV	—
bit 13					bit 8

R/P-1	R/P-1	R/P-1	U-1	U-1	U-1	R/P-1	R/P-1
BOREN1	BOREN0	$\overline{\text{LPBOREN}}$	—	—	—	$\overline{\text{PWRTE}}$	MCLRE
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	x = Bit is unknown	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	W = Writable bit	n = Value when blank or after Bulk Erase

bit 13 **$\overline{\text{DEBUG}}$**: Debugger Enable bit
1 = Background debugger disabled
0 = Background debugger enabled

bit 12 **STVREN**: Stack Overflow/Underflow Reset Enable bit
1 = Stack Overflow or Underflow will cause a Reset
0 = Stack Overflow or Underflow will not cause a Reset

bit 11 **PPS1WAY**: PPSLOCK One-Way Set Enable bit
1 = The PPSLOCK bit can be cleared and set only once; PPS registers remain locked after one clear/set cycle
0 = The PPSLOCK bit can be set and cleared repeatedly (subject to the unlock sequence)

bit 10 **ZCDDIS:** Zero-Cross Detect Disable bit
1 = ZCD disabled. ZCD can be enabled by setting the ZCDSEN bit of the ZCDCON register
0 = ZCD always enabled (ZCDSEN bit is ignored)

bit 9 **BORV**: Brown-out Reset Voltage Selection bit(1)
1 = Brown-out Reset voltage (VBOR) set to lower trip point level
0 = Brown-out Reset voltage (VBOR) set to higher trip point level

bit 8 **Unimplemented:** Read as '1'

bit 7-6 **BOREN<1:0>**: Brown-out Reset Enable bits
When enabled, Brown-out Reset Voltage (VBOR) is set by the BORV bit
11 = Brown-out Reset is enabled; SBOREN bit is ignored
10 = Brown-out Reset is enabled while running, disabled in Sleep; SBOREN bit is ignored
01 = Brown-out Reset is enabled according to SBOREN
00 = Brown-out Reset is disabled

bit 5 **$\overline{\text{LPBOREN}}$**: Low-Power BOR Enable bit
1 = ULPBOR is disabled
0 = ULPBOR is enabled

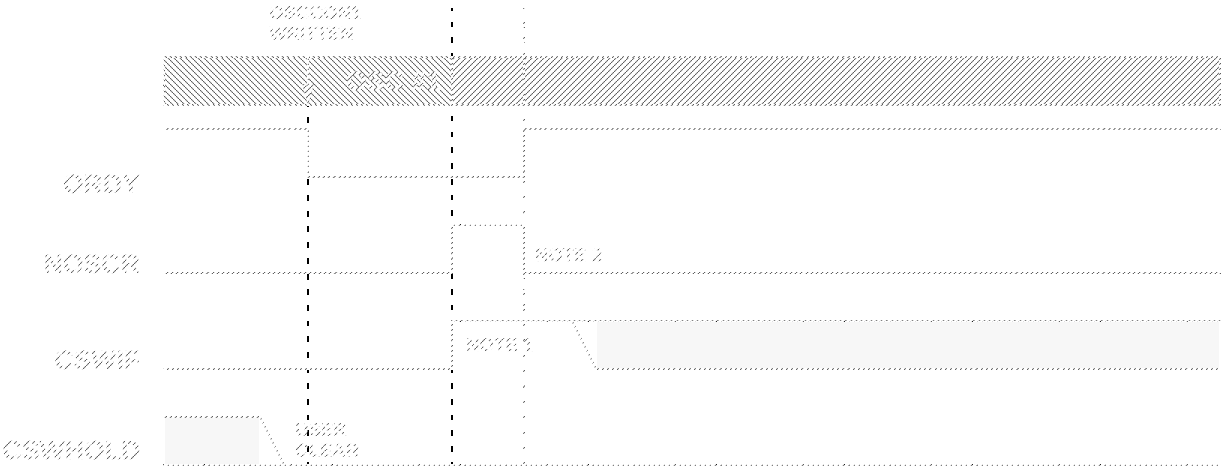
bit 4-2 **Unimplemented**: Read as '1'

bit 1 **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit
1 = PWRT is disabled
0 = PWRT is enabled

bit 0 **MCLRE**: Master Clear ($\overline{\text{MCLR}}$) Enable bit
If LVP = 1:
RE3 pin function is $\overline{\text{MCLR}}$ (it will reset the device when driven low)
If LVP = 0:
1 = $\overline{\text{MCLR}}$ pin is $\overline{\text{MCLR}}$ (it will reset the device when driven low)
0 = $\overline{\text{MCLR}}$ pin may be used as general purpose RE3 input

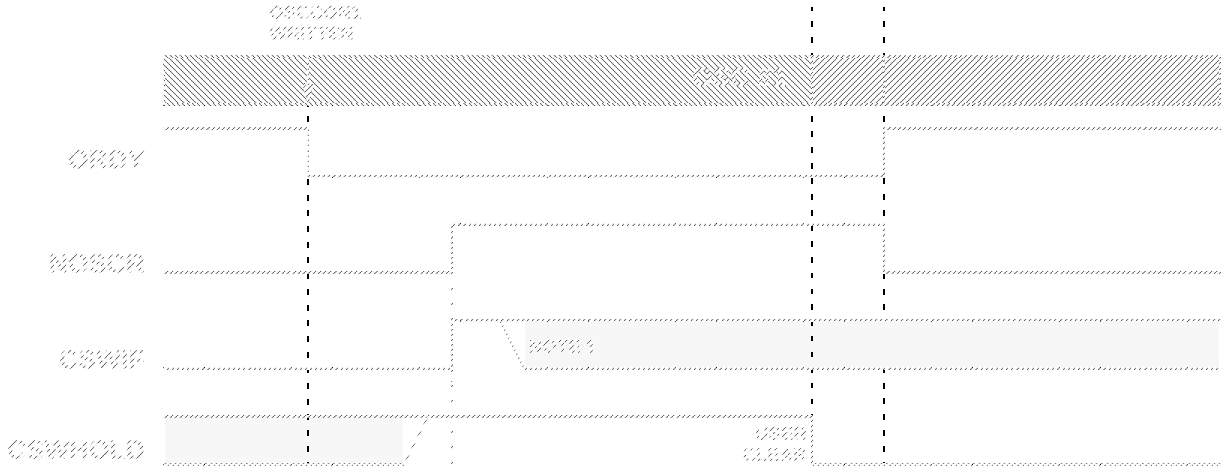
Note 1: See Vbor parameter for specific trip point voltages.
2: The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

FIGURE 9-5: CLOCK SWITCH (CSWHOLD = 0)



Note 1: CSWIF is asserted coincident with NOSCR; interrupt is serviced at OSC#2 speed.
2: The assertion of NOSCR is hidden from the user because it appears only for the duration of the switch.

FIGURE 9-6: CLOCK SWITCH (CSWHOLD = 1)



Note 1: CSWIF is asserted coincident with NOSCR, and may be cleared before or after clearing CSWHOLD = 0.

REGISTER 10-16: PIR6: PERIPHERAL INTERRUPT REQUEST REGISTER 6

U-0	U-0	U-0	U-0	U-0	U-0	R/W/HS-0/0	R/W/HS-0/0
—	—	—	—	—	—	CCP2IF	CCP1IF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HS = Hardware set

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **CCP2IF:** CCP2 Interrupt Flag bit

Value	CCPM Mode		
	Capture	**Compare**	**PWM**
1	Capture occurred (must be cleared in software)	Compare match occurred (must be cleared in software)	Output trailing edge occurred (must be cleared in software)
0	Capture did not occur	Compare match did not occur	Output trailing edge did not occur

bit 0 **CCP1IF:** CCP1 Interrupt Flag bit

Value	CCPM Mode		
	Capture	**Compare**	**PWM**
1	Capture occurred (must be cleared in software)	Compare match occurred (must be cleared in software)	Output trailing edge occurred (must be cleared in software)
0	Capture did not occur	Compare match did not occur	Output trailing edge did not occur

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

13.3.2 NVM UNLOCK SEQUENCE

The unlock sequence is a mechanism that protects the NVM from unintended self-write programming or erasing. The sequence must be executed and completed without interruption to successfully complete any of the following operations:

- PFM Row Erase
- Load of PFM write latches
- Write of PFM write latches to PFM memory
- Write of PFM write latches to User IDs

The unlock sequence consists of the following steps and must be completed in order:

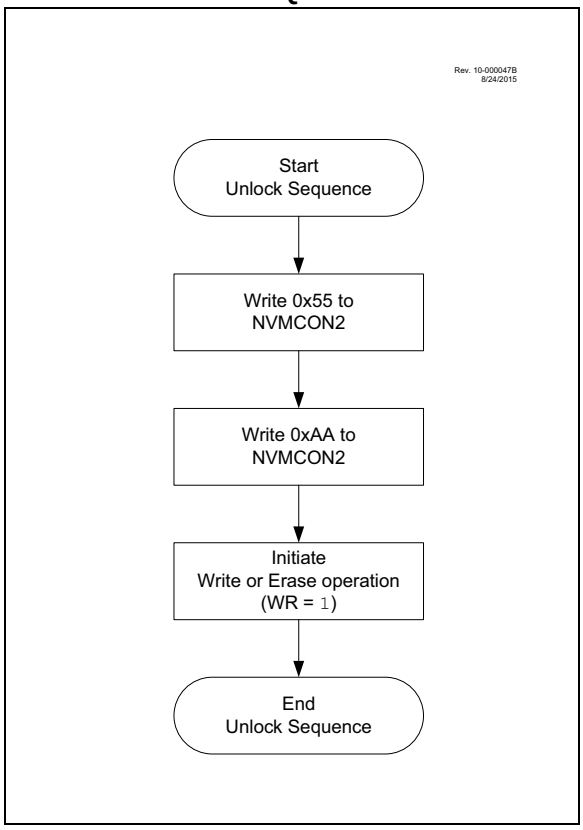
- Write 55h to NVMCON2
- Write AAh to NMVCON2
- Set the WR bit of NVMCON1

Once the WR bit is set, the processor will stall internal operations until the operation is complete and then resume with the next instruction.

Note:	The two NOP instructions after setting the WR bit that were required in previous devices are not required for PIC16(L)F15313/23 devices. See Figure 13-2.

Since the unlock sequence must not be interrupted, global interrupts should be disabled prior to the unlock sequence and re-enabled after the unlock sequence is completed.

FIGURE 13-2: NVM UNLOCK SEQUENCE FLOWCHART



EXAMPLE 13-2: NVM UNLOCK SEQUENCE

```
BCF      INTCON, GIE      ; Recommended so sequence is not interrupted
BANKSEL  NVMCON1          ;
BSF      NVMCON1, WREN    ; Enable write/erase
MOVLW    55h              ; Load 55h
MOVWF    NVMCON2          ; Step 1: Load 55h into NVMCON2
MOVLW    AAh              ; Step 2: Load W with AAh
MOVWF    NVMCON2          ; Step 3: Load AAH into NVMCON2
BSF      NVMCON1, WR      ; Step 4: Set WR bit to begin write/erase
BSF      INTCON, GIE      ; Re-enable interrupts
```

Note 1: Sequence begins when NVMCON2 is written; steps 1-4 must occur in the cycle-accurate order shown.

2: Opcodes shown are illustrative; any instruction that has the indicated effect may be used.

13.3.3 NVMREG ERASE OF PFM

Before writing to PFM, the word(s) to be written must be erased or previously unwritten. PFM can only be erased one row at a time. No automatic erase occurs upon the initiation of the write to PFM.

To erase a PFM row:

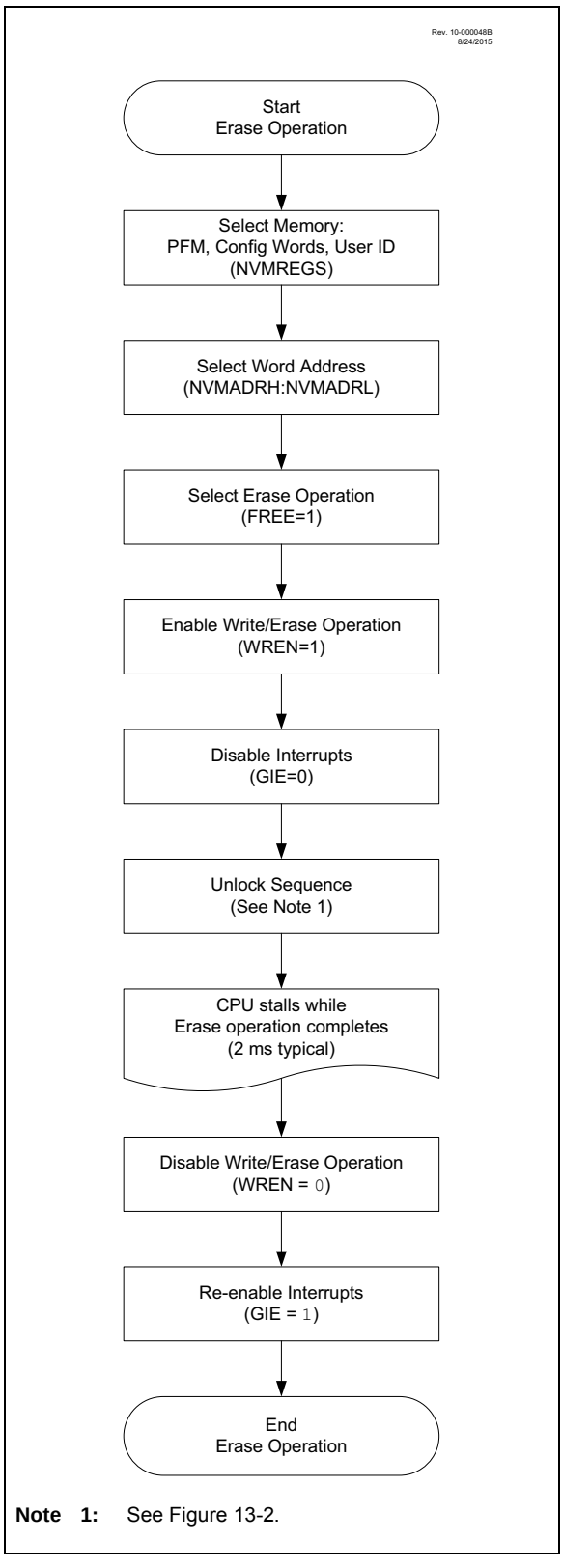
1. Clear the NVMREGS bit of the NVMCON1 register to erase PFM locations, or set the NMVREGS bit to erase User ID locations.
2. Write the desired address into the NVMADRH:NVMADRL register pair (Table 13-2).
3. Set the FREE and WREN bits of the NVMCON1 register.
4. Perform the unlock sequence as described in **Section 13.3.2 “NVM Unlock Sequence”**.

If the PFM address is write-protected, the WR bit will be cleared and the erase operation will not take place.

While erasing PFM, CPU operation is suspended, and resumes when the operation is complete. Upon completion, the NVMIF is set, and an interrupt will occur if the NVMIE bit is also set.

Write latch data is not affected by erase operations, and WREN will remain unchanged.

FIGURE 13-3: NVM ERASE FLOWCHART



Note 1: See Figure 13-2.

16.0 PERIPHERAL MODULE DISABLE

The PIC16(L)F15313/23 provides the ability to disable selected modules, placing them into the lowest possible Power mode.

For legacy reasons, all modules are ON by default following any Reset.

16.1 Disabling a Module

Disabling a module has the following effects:

- All clock and control inputs to the module are suspended; there are no logic transitions, and the module will not function.
- The module is held in Reset:
  - Writing to SFRs is disabled
  - Reads return 00h

16.2 Enabling a module

When the register bit is cleared, the module is re-enabled and will be in its Reset state; SFR data will reflect the POR Reset values.

Depending on the module, it may take up to one full instruction cycle for the module to become active. There should be no interaction with the module (e.g., writing to registers) for at least one instruction after it has been re-enabled.

16.3 Disabling a Module

When a module is disabled, all the associated PPS selection registers (Registers xxxPPS Register 15-1, 15-2, and 15-3), are also disabled.

16.4 System Clock Disable

Setting SYSCMD (PMD0, Register 16-1) disables the system clock (FOSC) distribution network to the peripherals. Not all peripherals make use of SYSCLK, so not all peripherals are affected. Refer to the specific peripheral description to see if it will be affected by this bit.

23.10 CWG1 Auto-shutdown Source

The output of the comparator module can be used as an auto-shutdown source for the CWG1 module. When the output of the comparator is active and the corresponding ASxE is enabled, the CWG operation will be suspended immediately (see **Section 30.10 "Auto-Shutdown"**).

23.11 Operation in Sleep Mode

The comparator module can operate during Sleep. The comparator clock source is based on the Timer1 clock source. If the Timer1 clock source is either the system clock (FOSC) or the instruction clock (FOSC/4), Timer1 will not operate during Sleep, and synchronized comparator outputs will not operate.

A comparator interrupt will wake the device from Sleep. The CxIE bits of the PIE2 register must be set to enable comparator interrupts.

REGISTER 26-4: T1GATE TIMER1 GATE SELECT REGISTER

U-0	U-0	U-0	R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u
—	—	—	GSS<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	HC = Bit is cleared by hardware

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **GSS<4:0>:** Timer1 Gate Select bits

11111-10001 = Reserved
10000 = LC4_out
01111 = LC3_out
01110 = LC2_out
01101 = LC1_out
00100 = ZCD1_output
01011 = C2OUT_sync
01010 = C1OUT_sync
01001 = NCO1_out
01000 = PWM6_out
00111 = PWM5_out
00110 = PWM4_out
00101 = PWM3_out
00100 = CCP2_out
00011 = CCP1_out
00010 = TMR2_postscaled
00001 = Timer0 overflow output
00000 = T1GPPS

27.5.8 LEVEL RESET, EDGE-TRIGGERED HARDWARE LIMIT ONE-SHOT MODES

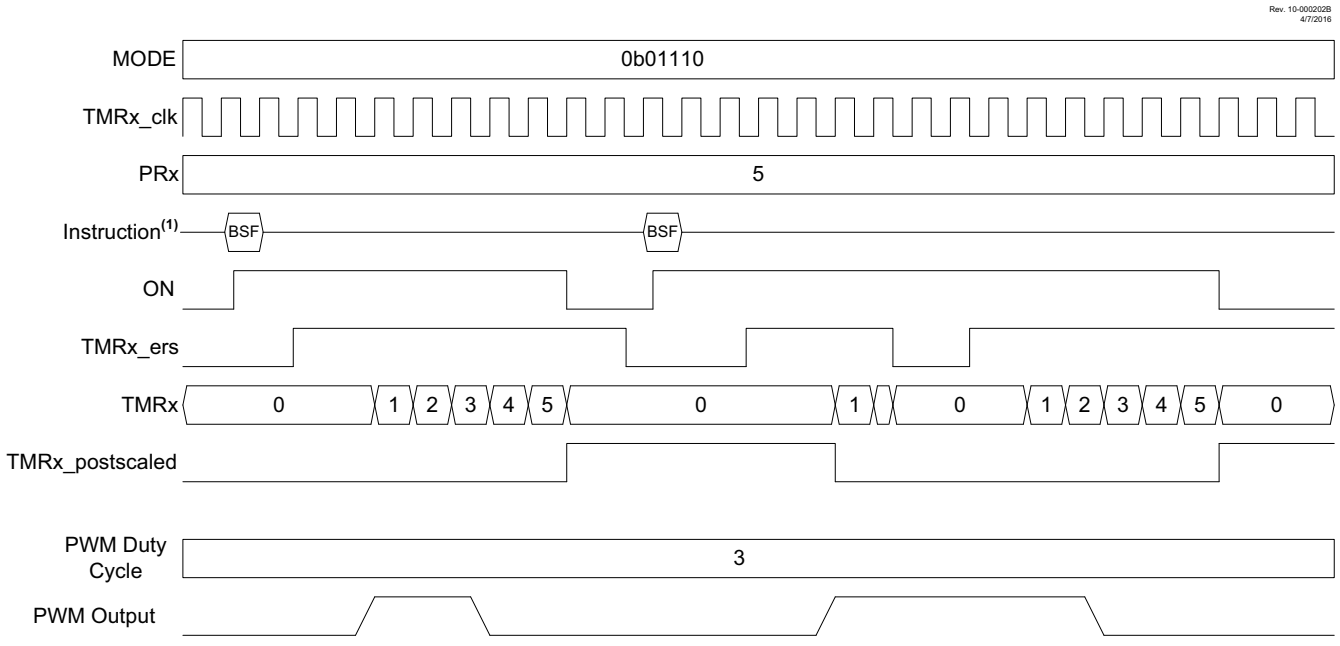
In Level -Triggered One-Shot mode the timer count is reset on the external signal level and starts counting on the rising/falling edge of the transition from Reset level to the active level while the ON bit is set. Reset levels are selected as follows:

- Low Reset level (MODE<4:0> = 01110)
- High Reset level (MODE<4:0> = 01111)

When the timer count matches the PRx period count, the timer is reset and the ON bit is cleared. When the ON bit is cleared by either a PRx match or by software control a new external signal edge is required after the ON bit is set to start the counter.

When Level-Triggered Reset One-Shot mode is used in conjunction with the CCP PWM operation the PWM drive goes active with the external signal edge that starts the timer. The PWM drive goes inactive when the timer count equals the CCPRx pulse width count. The PWM drive does not go active when the timer count clears at the PRx period count match.

FIGURE 27-11: LOW LEVEL RESET, EDGE-TRIGGERED HARDWARE LIMIT ONE-SHOT MODE TIMING DIAGRAM (MODE = 01110)



Note 1: BSF and BCF represent Bit-Set File and Bit-Clear File instructions executed by the CPU to set or clear the ON bit of TxCON. CPU execution is asynchronous to the timer clock input.

32.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP1) MODULE

32.1 MSSP Module Overview

The Master Synchronous Serial Port (MSSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The MSSP module can operate in one of two modes:

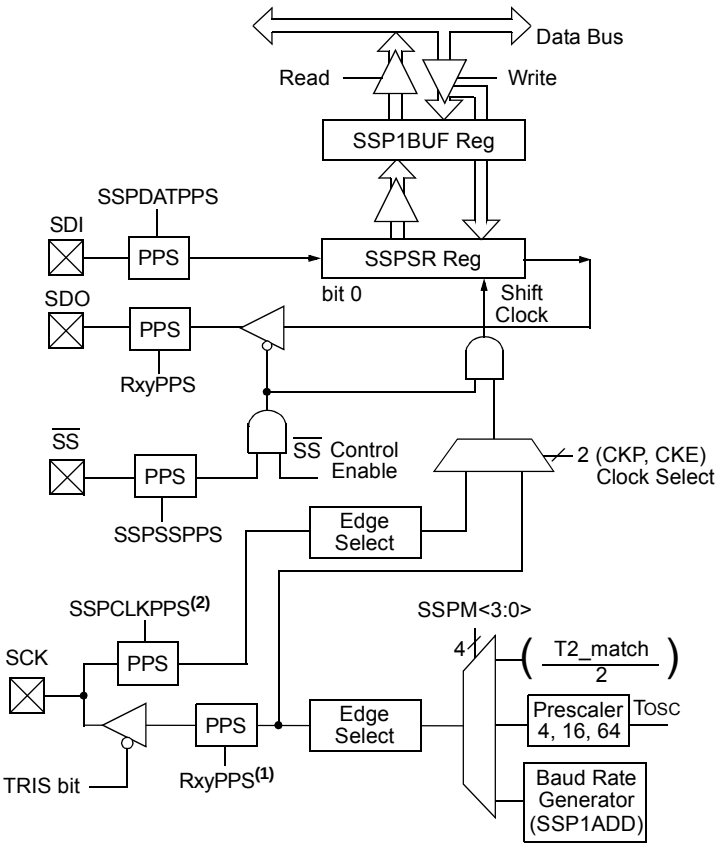
- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C)

The SPI interface supports the following modes and features:

- Master mode
- Slave mode
- Clock Parity
- Slave Select Synchronization (Slave mode only)
- Daisy-chain connection of slave devices

Figure 32-1 is a block diagram of the SPI interface module.

FIGURE 32-1: MSSP BLOCK DIAGRAM (SPI MODE)



Note 1: Output selection for master mode.
2: Input selection for slave mode.

32.2 SPI Mode Overview

The Serial Peripheral Interface (SPI) bus is a synchronous serial data communication bus that operates in Full-Duplex mode. Devices communicate in a master/slave environment where the master device initiates the communication. A slave device is controlled through a Chip Select known as Slave Select.

The SPI bus specifies four signal connections:

- Serial Clock (SCK)
- Serial Data Out (SDO)
- Serial Data In (SDI)
- Slave Select ($\overline{SS}$)

Figure 32-1 shows the block diagram of the MSSP module when operating in SPI mode.

The SPI bus operates with a single master device and one or more slave devices. When multiple slave devices are used, an independent Slave Select connection is required from the master device to each slave device.

Figure 32-4 shows a typical connection between a master device and multiple slave devices.

The master selects only one slave at a time. Most slave devices have tri-state outputs so their output signal appears disconnected from the bus when they are not selected.

Transmissions involve two shift registers, eight bits in size, one in the master and one in the slave. Data is always shifted out one bit at a time, with the Most Significant bit (MSb) shifted out first. At the same time, a new Least Significant bit (LSb) is shifted into the same register.

Figure 32-5 shows a typical connection between two processors configured as master and slave devices.

Data is shifted out of both shift registers on the programmed clock edge and latched on the opposite edge of the clock.

The master device transmits information out on its SDO output pin which is connected to, and received by, the slave's SDI input pin. The slave device transmits information out on its SDO output pin, which is connected to, and received by, the master's SDI input pin.

To begin communication, the master device first sends out the clock signal. Both the master and the slave devices should be configured for the same clock polarity.

The master device starts a transmission by sending out the MSb from its shift register. The slave device reads this bit from that same line and saves it into the LSb position of its shift register.

During each SPI clock cycle, a full-duplex data transmission occurs. This means that while the master device is sending out the MSb from its shift register (on its SDO pin) and the slave device is reading this bit and saving it as the LSb of its shift register, that the slave device is also sending out the MSb from its shift register (on its SDO pin) and the master device is reading this bit and saving it as the LSb of its shift register.

After eight bits have been shifted out, the master and slave have exchanged register values.

If there is more data to exchange, the shift registers are loaded with new data and the process repeats itself.

Whether the data is meaningful or not (dummy data), depends on the application software. This leads to three scenarios for data transmission:

- Master sends useful data and slave sends dummy data.
- Master sends useful data and slave sends useful data.
- Master sends dummy data and slave sends useful data.

Transmissions may involve any number of clock cycles. When there is no more data to be transmitted, the master stops sending the clock signal and it deselects the slave.

Every slave device connected to the bus that has not been selected through its slave select line must disregard the clock and transmission signals and must not transmit out any data of its own.

33.3.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII "U") which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUD1CON register starts the auto-baud calibration sequence. While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SP1BRG begins counting up using the BRG counter clock as shown in Figure 33-6. The fifth rising edge will occur on the RX pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SP1BRGH, SP1BRGL register pair, the ABDEN bit is automatically cleared and the RX1IF interrupt flag is set. The value in the RC1REG needs to be read to clear the RX1IF interrupt. RC1REG content should be discarded. When calibrating for modes that do not use the SP1BRGH register the user can verify that the SP1BRGL register did not overflow by checking for 00h in the SP1BRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 33-1. During ABD, both the SP1BRGH and SP1BRGL registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SP1BRGH and SP1BRGL registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 33.3.3 "Auto-Wake-up on Break"**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

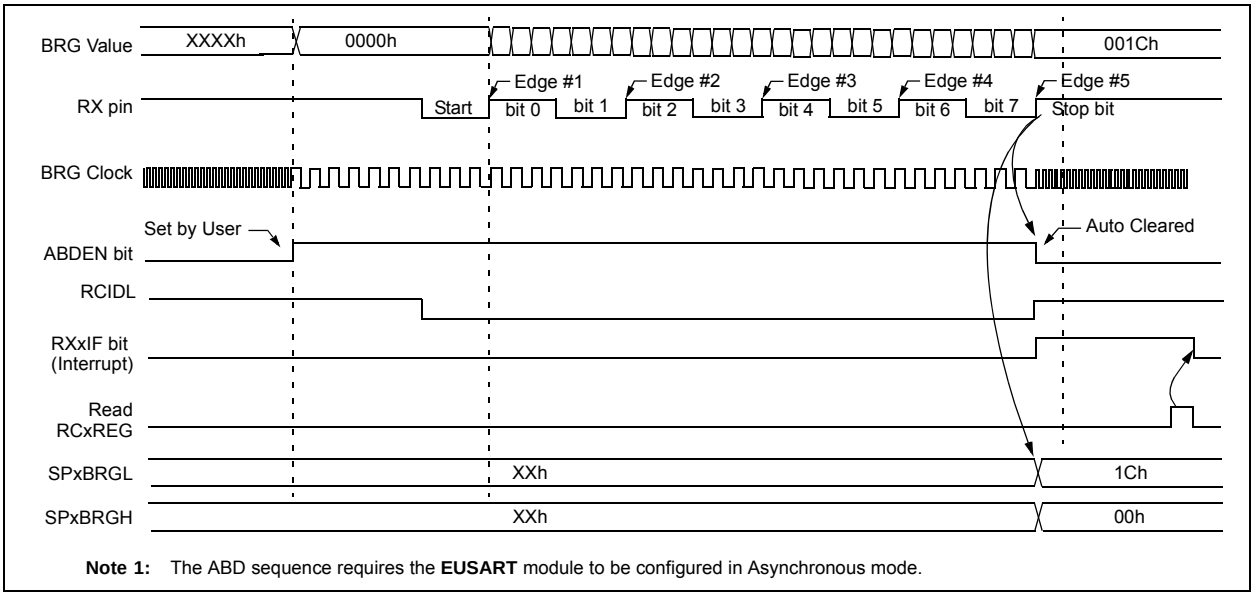
3: During the auto-baud process, the auto-baud counter starts counting at one. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SP1BRGH:SP1BRGL register pair.

TABLE 33-1: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	FOSC/64	FOSC/512
0	1	FOSC/16	FOSC/128
1	0	FOSC/16	FOSC/128
1	1	FOSC/4	FOSC/32

Note: During the ABD sequence, SP1BRGL and SP1BRGH registers are both used as a 16-bit counter, independent of the BRG16 setting.

FIGURE 33-6: AUTOMATIC BAUD RATE CALIBRATION



Note 1: The ABD sequence requires the **EUSART** module to be configured in Asynchronous mode.

FIGURE 37-19: SPI SLAVE MODE TIMING (CKE = 0)

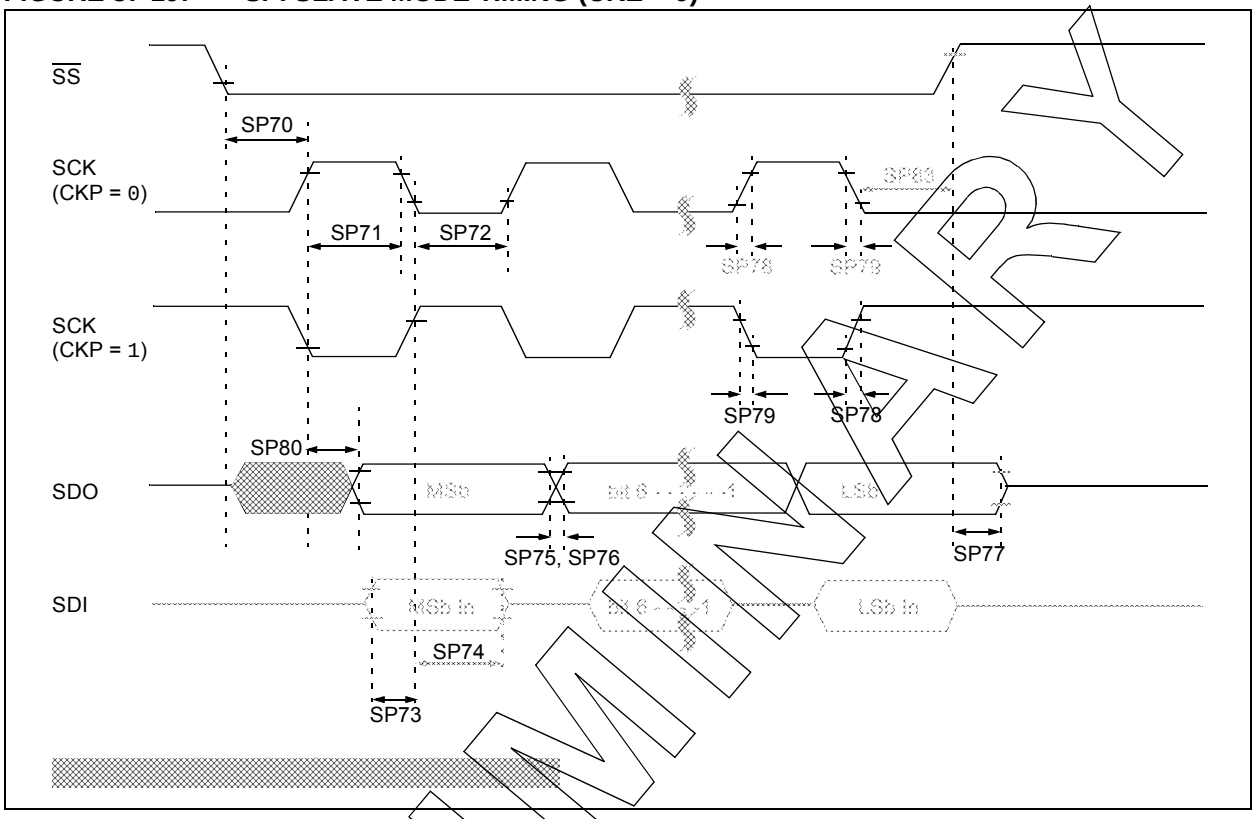
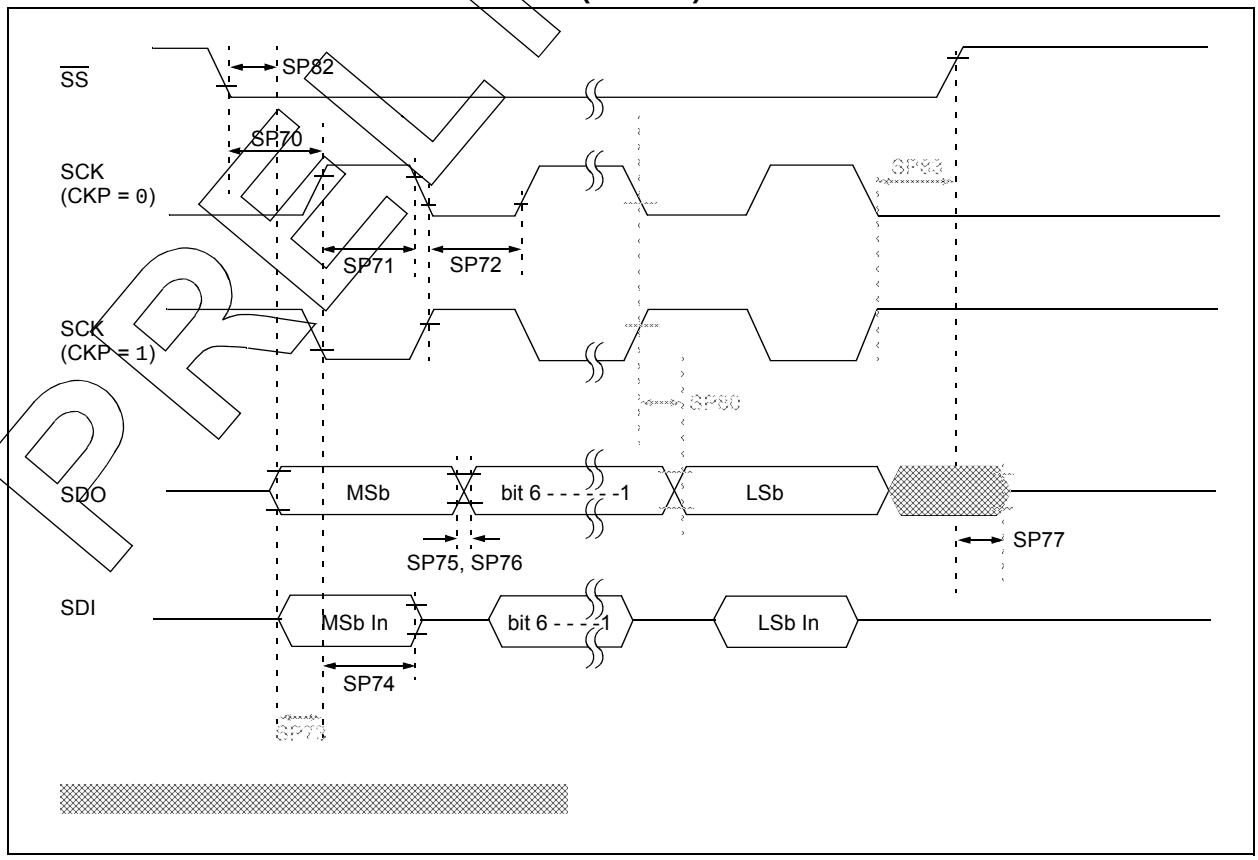
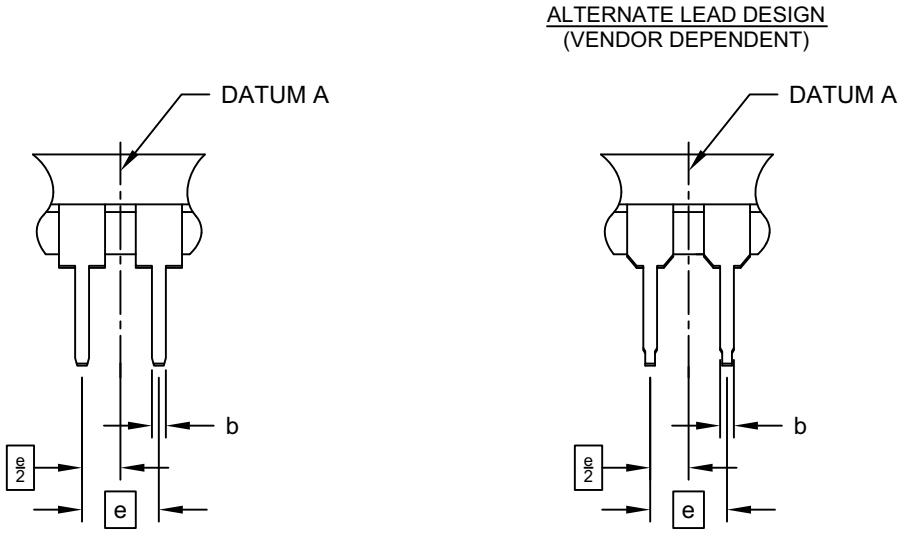


FIGURE 37-20: SPI SLAVE MODE TIMING (CKE = 1)



8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		.100 BSC	
Top to Seating Plane	A	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	-	-	.430

Notes:

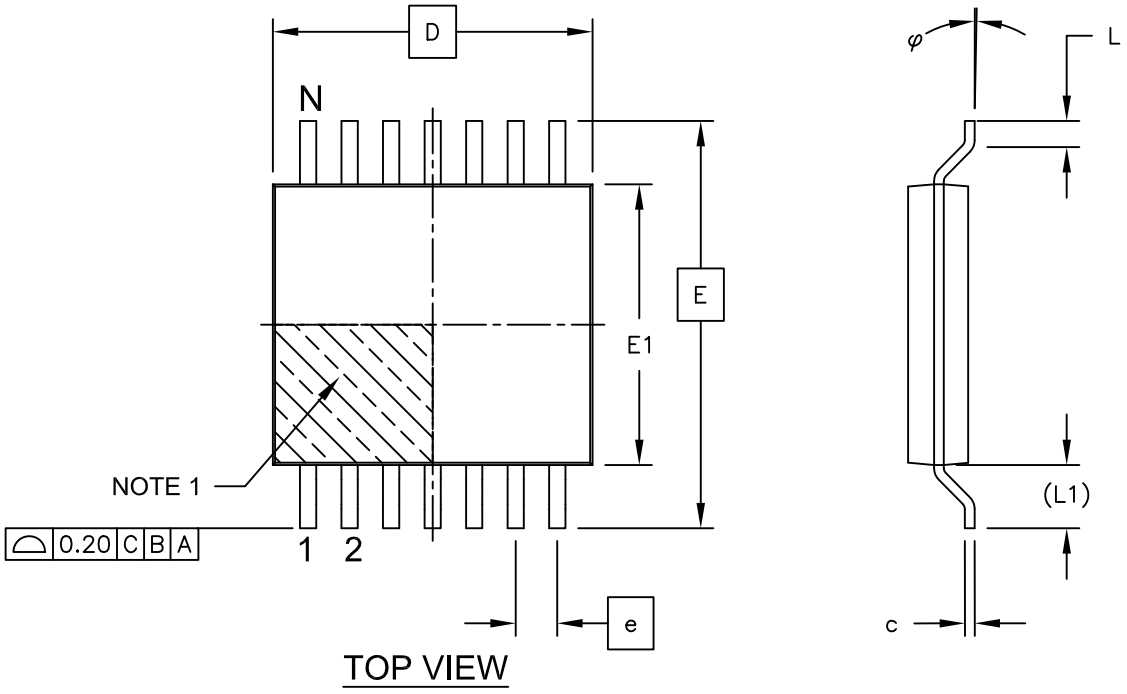
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M

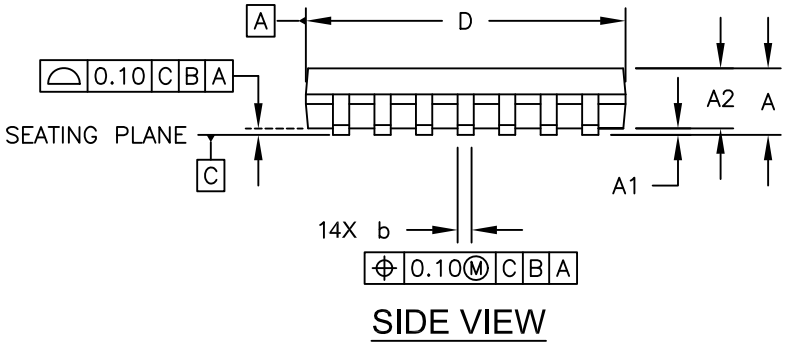
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-018D Sheet 2 of 2

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Microchip Technology Drawing C04-087C Sheet 1 of 2

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
═ ISO/TS 16949 ═

Trademarks

ISBN: 978-1-5224-1620-3